

AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS

1. Cancelled.
2. (Currently Amended) The layered heater according to Claim [[1]] 15, wherein the spacing is constant.
3. (Currently Amended) The layered heater according to Claim [[1]] 15, wherein the spacing is variable.
4. (Currently Amended) The layered heater according to Claim [[1]] 15, wherein the resistive circuit pattern further comprises a width that is constant.
5. (Currently Amended) The layered heater according to Claim [[1]] 15, wherein the resistive circuit pattern further comprises a width that is variable.
6. (Currently Amended) The layered heater according to Claim [[1]] 15, wherein the layered heater is selected from a group consisting of thick film, thin film, thermal spray, and sol-gel.
7. (Currently Amended) The layered heater according to Claim [[1]] 15, wherein the resistive circuit pattern is selected from a group consisting of series, parallel, and series-parallel.
8. (Currently Amended) The layered heater according to Claim [[1]] 15, wherein the variable thickness is continuous.

9. (Currently Amended) The layered heater according to Claim [[1]] 15, wherein the variable thickness is non-continuous.

10. (Currently Amended) A layered heater comprising:
a dielectric layer;
at least one resistive layer formed on the dielectric layer, the resistive layer comprising a resistive circuit pattern, the resistive circuit pattern defining a trace having a width and a spacing; and
a protective layer formed on the at least one resistive layer,
wherein a thickness of the resistive circuit pattern varies across the width of the trace of the resistive circuit pattern for a variable watt density.

11-14. Cancelled.

15. (Currently Amended) A layered heater comprising:
a dielectric layer;
a resistive layer formed on the dielectric layer, the resistive layer comprising a resistive circuit pattern, the resistive circuit pattern defining a trace having a length, ~~[[and]]~~ a thickness, and a spacing; and
a protective layer formed on the resistive layer,
wherein the thickness of the resistive circuit pattern varies along the length of the trace of the resistive circuit pattern for a variable watt density.

16. (Currently Amended) A layered heater comprising:
a substrate;
a dielectric layer formed on the substrate;
a resistive layer formed on the dielectric layer, the resistive layer comprising a resistive circuit pattern, the resistive circuit pattern defining a trace having a length and a thickness; and
a protective layer formed on the resistive layer,
wherein the thickness of the resistive circuit pattern varies along the length of the trace of the resistive circuit pattern for a variable watt density.

17-19. Cancelled.

20. (Withdrawn) A method of forming a resistive circuit pattern of a layered heater, the method comprising the steps of:
(a) dispensing a conductive ink at a rate onto a surface; and
(b) varying the dispensing rate of the conductive ink to form a variable thickness resistive circuit pattern.

21. (Withdrawn) A method of forming a resistive circuit pattern of a layered heater, the method comprising the steps of:
(a) dispensing a conductive ink at a rate onto a surface; and
(b) varying a feed speed of the substrate relative to the dispensing of conductive ink to form a variable thickness resistive circuit pattern.

22. (Withdrawn) A method of forming a resistive circuit pattern of a layered heater, the method comprising the steps of:

- (a) dispensing a conductive ink at a rate onto a surface;
- (b) varying the dispensing rate of the conductive ink; and
- (c) varying a feed speed of the substrate relative to the dispensing of

conductive ink,

wherein a variable thickness resistive circuit pattern is produced.

23. (Withdrawn) A method of forming a resistive circuit pattern of a layered heater, the method comprising the steps of:

- (a) applying a volume of conductive ink onto a surface to form a trace;

and

- (b) applying an additional volume of conductive ink onto the trace,

wherein a variable thickness resistive circuit pattern is produced.

24. (Withdrawn) The method according to Claim 23, wherein the volumes of conductive ink are applied by a layered process selected from the group consisting of thick film, thin film, thermal spraying, and sol-gel.

25. (Withdrawn) The method according to Claim 23, wherein the volumes of conductive ink are applied using precision pen writing equipment.

26. (Withdrawn) The method according to Claim 23, wherein the volumes of conductive ink are applied using a silk screening process.

27. Cancelled.